

REGULATORY COMPLIANCE











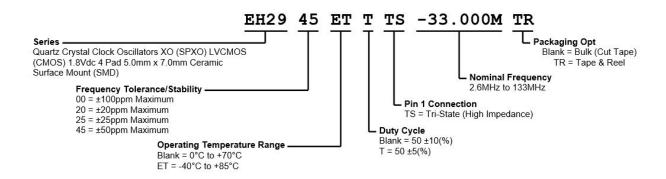
ITEM DESCRIPTION

Quartz Crystal Clock Oscillators XO (SPXO) LVCMOS (CMOS) 1.8Vdc 4 Pad 5.0mm x 7.0mm Ceramic Surface Mount (SMD)

ELECTRICAL SPECIFICAT	FIONS CONTRACTOR OF THE PROPERTY OF THE PROPER
Nominal Frequency	2.6MHz to 133MHz
Frequency Tolerance/Stability	Inclusive of all conditions: Calibration Tolerance at 25°C, Frequency Stability over the Operating Temperature Range, Supply Voltage Change, Output Load Change, First Year Aging at 25°, 260°C Reflow, Shock, and Vibration ±100ppm Maximum ±20ppm Maximum ±25ppm Maximum ±50ppm Maximum
Aging at 25°C	±5ppm/year Maximum
Operating Temperature Range	0°C to +70°C -40°C to +85°C
Supply Voltage	1.8Vdc ±5%
Input Current	No Load 3.5mA Maximum over Nominal Frequency of 2.6MHz to 25MHz 4mA Maximum over Nominal Frequency of 25.000001MHz to 75MHz 5mA Maximum over Nominal Frequency of 75.000001MHz to 100MHz 8mA Maximum over Nominal Frequency of 100.000001MHz to 133MHz
Output Voltage Logic High (V _{он})	IOH = -8mA 90% of Vdd Minimum
Output Voltage Logic Low (V _{OL})	IOL = +8mA 10% of Vdd Maximum
Rise/Fall Time	Measured at 20% to 80% of waveform 6nSec Maximum over Nominal Frequency of 2.6MHz to 50MHz 4nSec Maximum over Nominal Frequency of 50.000001MHz to 75MHz 2nSec Maximum over Nominal Frequency of 75.000001MHz to 133MHz
Duty Cycle	Measured at 50% of waveform 50 ±10(%) 50 ±5(%) (Only available over Nominal Frequency range of 2.6MHz to 50MHz)
Load Drive Capability	15pF Maximum
Output Logic Type	CMOS
Pin 1 Connection	Tri-State (High Impedance)
Tri-State Input Voltage (Vih and Vil)	90% of Vdd Minimum or No Connect to Enable Output, 10% of Vdd Maximum to Disable Output (High Impedance)
Standby Current	10μA Maximum (Pin 1 = Ground)
RMS Phase Jitter	Fj = 12kHz to 20MHz 20pSec Typical, 30pSec Maximum
Period Jitter (RMS)	15pSec Typical
Period Jitter (pk-pk)	100pSec Typical, 200pSec Maximum
Start Up Time	10mSec Maximum
Storage Temperature Range	-55°C to +125°C

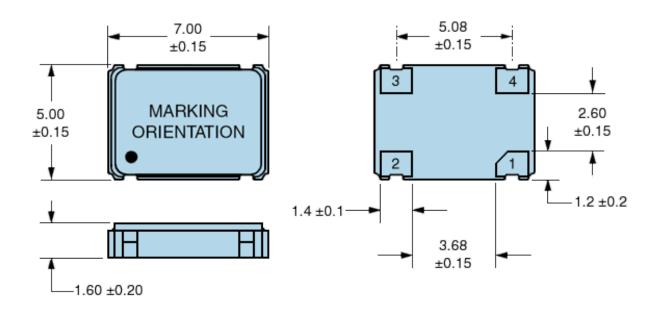


PART NUMBERING GUIDE

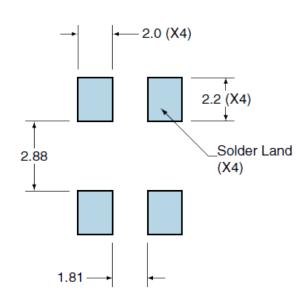




MECHANICAL DIMENSIONS



SUGGESTED SOLDER PAD LAYOUT



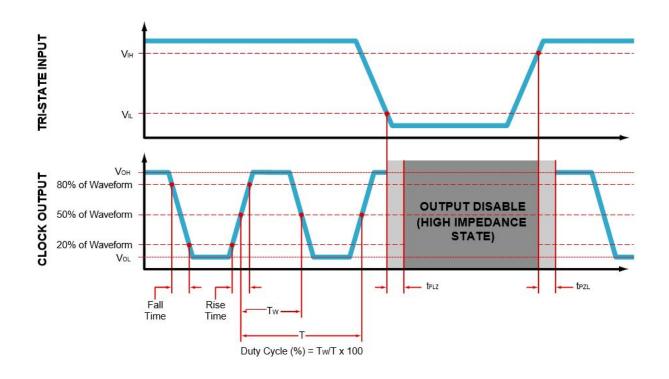
PIN	CONNECTION
1	Tri-State
2	Case Ground
3	Output
4	Supply Voltage

All Tolerances are ±0.1

All Dimensions in Millimeters

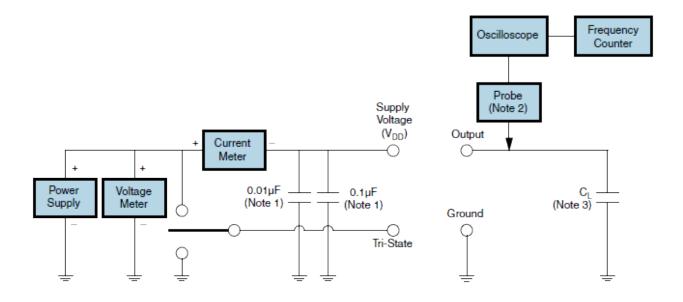


OUTPUT WAVEFORM & TIMING DIAGRAM





TEST CIRCUIT FOR CMOS OUTPUT



Note 1: An external 0.01µF ceramic bypass capacitor in parallel with a 0.1µF high frequency ceramic bypass capacitor close (less Than 2mm) to the package ground and supply voltage pin is required.

Note 2: A low capacitance (<12pF), 10X attenuation factor, high impedance (>10Mohms), and high bandwidth (>300MHz) passive Probe is recommended.

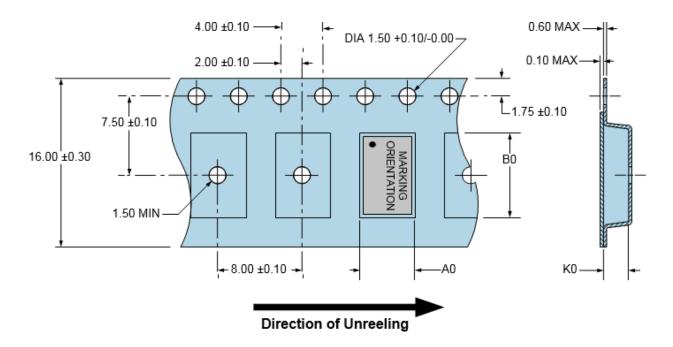
Note 3: Capacitance value CL includes sum of all probe and fixture capacitance.

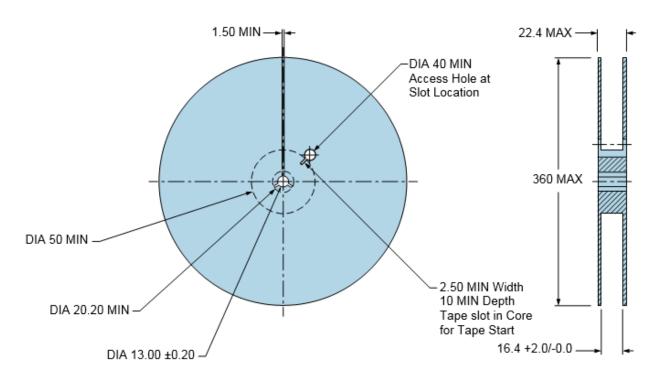


TAPE & REEL DIMENSIONS

Quantity per Reel: 1,000 Units

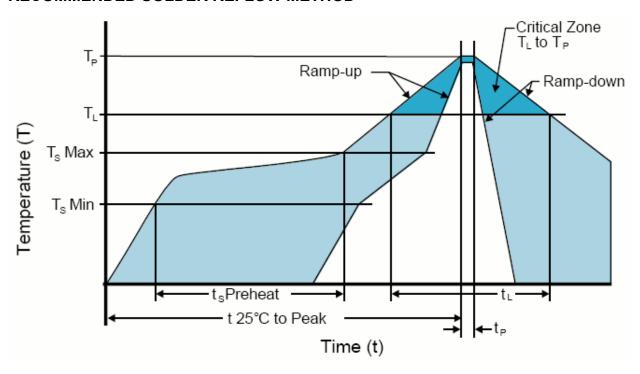
All Dimensions in Millimeters
Compliant to EIA-481







RECOMMENDED SOLDER REFLOW METHOD



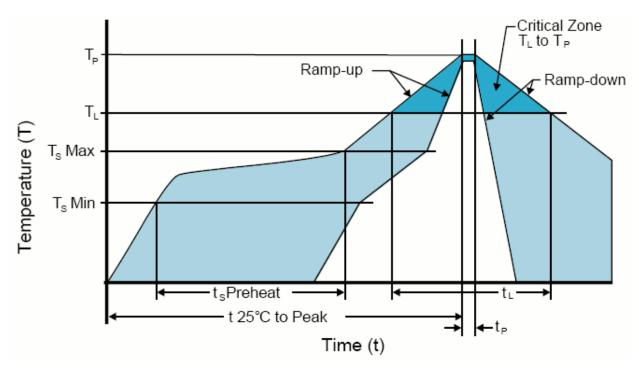
HIGH TEMPERATURE INFRARED/CONVECTION		
TS MAX to TL (Ramp-up Rate)	3°C/Second Maximum	
Preheat		
- Temperature Minimum (T _s MIN)	150°C	
- Temperature Typical (T _s TYP)	175°C	
- Temperature Maximum(T _s MAX)	200°C	
- Time (t _s MIN)	60 - 180 Seconds	
Ramp-up Rate (TL to TP)	3°C/Second Maximum	
Time Maintained Above:		
- Temperature (T _L)	217°C	
- Time (t _L)	60 - 150 Seconds	
Peak Temperature (TP)	260°C Maximum for 10 Seconds Maximum	
Target Peak Temperature(TP Target)	250°C +0/-5°C	
Time within 5°C of actual peak (tp)	20 - 40 Seconds	
Ramp-down Rate	6°C/Second Maximum	
Time 25°C to Peak Temperature (t)	8 Minutes Maximum	
Moisture Sensitivity Level	Level 1	
Additional Notes	Temperatures shown are applied to body of device.	

High Temperature Manual Soldering

260°C Maximum for 5 Seconds Maximum, 2 times Maximum. (Temperatures shown are applied to body of device.)



RECOMMENDED SOLDER REFLOW METHOD



LOW TEMPERATURE INFRARED/CONVECTION 240°C		
TS MAX to TL (Ramp-up Rate)	5°C/Second Maximum	
Preheat		
- Temperature Minimum (T _s MIN)	N/A	
- Temperature Typical (T _s TYP)	150°C	
- Temperature Maximum(T _s MAX)	N/A	
- Time (t _s MIN)	60 - 120 Seconds	
Ramp-up Rate (TL to TP)	5°C/Second Maximum	
Time Maintained Above:		
- Temperature (T _L)	150°C	
- Time (t _L)	200Seconds Maximum	
Peak Temperature (TP)	240°C	
Target Peak Temperature(TP Target)	240°C Maximum 2 Times/230°C Maximum 1Time	
Time within 5°C of actual peak (tp)	10 Seconds Maximum 2 Times / 80 Seconds Maximum 1 Time	
Ramp-down Rate	5°C/Second Maximum	
Time 25°C to Peak Temperature (t)	N/A	
Moisture Sensitivity Level	Level 1	
Additional Notes	Temperatures shown are applied to body of device.	

Low Temperature Manual Soldering

185°C Maximum for 10 Seconds Maximum, 2 times Maximum. (Temperatures shown are applied to body of device.)

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